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Panel discussions: “Cool chips for the next decade”

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Abstract:

The advance of CMOS process is still going, but the end is coming into sight. Semiconductor chips with advanced process later than 21nm are so expensive that they are developed only for million selling products. On the other hand, the advanced AI, IoT and big data technologies require more and more computation/communication power with a tightly limited power budget. How we can develop a “Cool chips” in the next decade? And how can the conference “Cool chips” contribute?

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